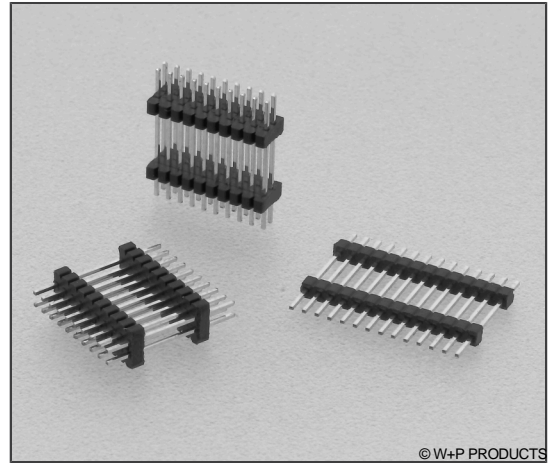


# 46-722 Economy Version

Sandwich-Stiftleisten RM 1,00mm, 1-/2-reihig  
Dual Body Pin Headers, 1.00mm Pitch, Single/Double Row

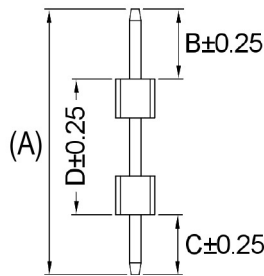
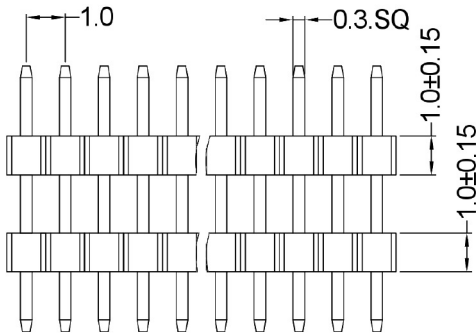
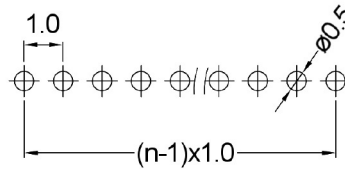
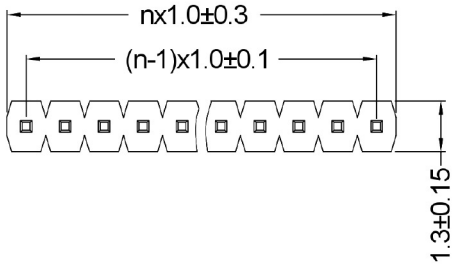
## Technische Daten / Technical Data

Isolierkörper	Thermoplast, nach UL94 V-0
Insulator	Thermoplastic, rated UL94 V-0
Kontaktmaterial	Kupferlegierung
Contact Material	Copper alloy
Kontaktoberfläche	Au über Ni
Contact Surface	Au over Ni
Durchgangswiderstand	< 30 mΩ
Contact Resistance	< 30 mΩ
Isolationswiderstand	> 500 MΩ
Insulation Resistance	> 500 MΩ
Spannungsfestigkeit	500 V AC/DC
Test Voltage	500 V AC/DC
Nennstrom	0,75 A
Current Rating	0.75 A
Temperaturbereich	-40 °C ~ +105 °C
Temperature Range	-40 °C ~ +105 °C
Verarbeitung	260 °C für 10 sec. / 230 °C für 30-60 sec.
Processing	260 °C for 10 sec. / 230 °C for 30-60 sec.



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Recommended P.C.B Layout (Top Side)  
(PCB BOARD TOLERANCE ±0.05)

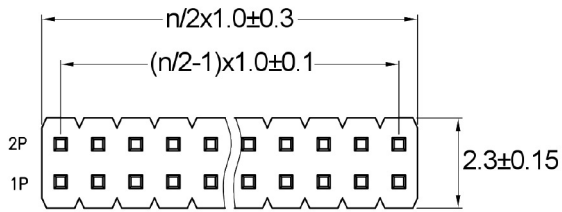


Series	Contacts*	Rows	Dimensions*	Plating
<b>46-722</b>	<b>010</b> 001-050 Einreihig Single row	<b>1</b> 1 Einreihig Single row	<b>10</b> 10 B=2.00 C=2.50 D=6.50mm A [mm] Andere Längen auf Anfrage Other lengths on request	<b>00</b> 00 Vergoldet Gold plated

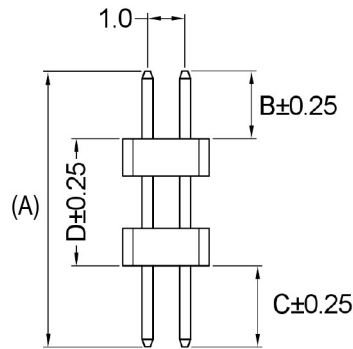
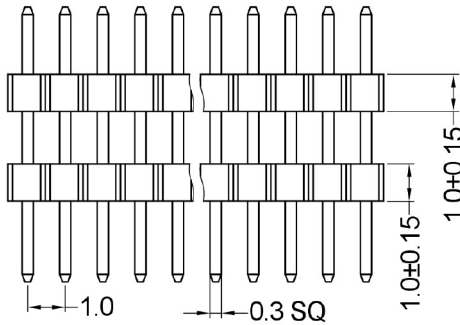
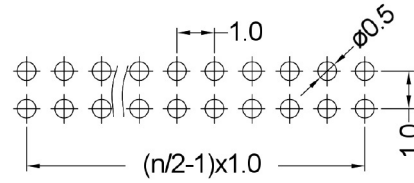
# 46-722 Economy Version

Sandwich-Stiftleisten RM 1,00mm, 1-/2-reihig

Dual Body Pin Headers, 1.00mm Pitch, Single/Double Row



Recommended P.C.B Layout (Top Side)  
(PCB BOARD TOLERANCE ±0.05)



Series

**46-722**

Contacts\*

**020**

004-050 Zweireihig  
Double row

Rows

**2**

2 Zweireihig  
Double row

Dimensions\*

**10**

10 B=2.00 C=2.50 D=6.50mm  
A [mm] Andere Längen auf Anfrage  
Other lengths on request

Plating

**00**

00 Vergoldet  
Gold plated

\* Dies ist ein **Bestellbeispiel** -  
bitte durch Ihre Spezifikationen ersetzen.  
\* This is an **order example** -  
please replace by your specifications.

### Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum $T_{Smin}$	150 °C
Temperatur Maximum $T_{Smax}$	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich $T_L$	untere Temperaturangabe [°C]
Verweildauer oberhalb $T_L$	laut Angabe im Datenblatt [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur $T_P$	obere Temperaturangabe [°C]
Dauer Höchsttemperatur	laut Angabe im Datenblatt [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur $T_P$	max. 8m

### Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature $T_{Smin}$	150 °C
Maximum Temperatur $T_{Smax}$	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature $T_L$	Lower Temperature [°C]
Duration above $T_L$	Acc. to datasheet [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature $T_P$	Upper Temperature [°C]
Duration Peak Temperature	Acc. to datasheet [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. $T_P$	max. 8min

